



ENGRAVING & ETCHING

ENGRAVING & ETCHING

Reprochem is producing coatings and chemicals for different laser sources, autotypical UV lamps system, and the "green line" ecoresist that can be developed in water base products

ENGRAVING PRODUCT ACCESSORIES



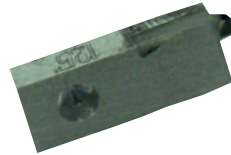
HIGH QUALITY ENGRAVING
STYLUS FOR HELIO MACHINES
4KHz OR 8KHz - ONE WAY
(TOP SERIES)



HIGH QUALITY ENGRAVING
STYLUS FOR OHIO AND
GRAVOSTAR MACHINES 4KHz OR
8KHz - ONE WAY (TOP SERIES)



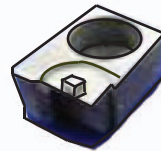
HIGH QUALITY ENGRAVING
STYLUS FOR HELIO MACHINES
4KHz OR 8KHz - ONE WAY
(STANDARD SERIES)



HIGH QUALITY ENGRAVING STYLUS
FOR OHIO AND GRAVOSTAR
MACHINES 4KHz OR 8KHz - ONE WAY
(STANDARD SERIES)



HELIO SLIDING SHOE



OHIO SLIDING SHOE



HELIO BURR CUTTER



OHIO BURR CUTTER

ENGRAVING & ETCHING



LUBRICATING SOLUTION T4 AND T6
Lubricant solution to apply on Copper cylinder surface before engraving. Suitable to have a better Copper cutting, it improves the diamond life.



LUBRICATING SOLUTION V4 AND V6
Lubricant solution to apply on Copper cylinder surface before engraving. Suitable to have a better Copper cutting, it improves the engraving diamond life.



LUBRICATING SOLUTION H-K FOR ENGRAVING TYPES NS
Water based coating to apply on Copper cylinder surface before engraving. Suitable to have a better Copper cutting, it improves engraving diamond life.

PHOTORESIST



PHOTORESIST R-100/NS
UV Negative Photoresist for Copper and Steel. UV Absorption 340-380 nm. Available for spray and ring coating. Solvent based.



PHOTORESIST R-300/NS
UV Negative Photoresist for Copper and Steel. UV Absorption 340-380 nm. Suitable for ring coating, with fast drying time. Solvent based.



PHOTORESIST R-410
UV Negative Photoresist for Copper and Steel. UV Absorption 340-410 nm. Available for spray and ring coating. Rubber based polymer with good steel adhesion.



ECORESIST E-100
UV Negative Photoresist for Copper and Steel. UV Absorption 340-410 nm. Coloured product with water based developer. Available for spray and ring coating.

ENGRAVING & ETCHING



PHOTORESIST THINNER
Thinner with high pure solvents to dilute the Photoresist in function of the application system.



PHOTORESIST DEVELOPER
Dye Developer to remove the not exposed area and to colour the exposed area to allow the control of the job surface.



ECORESIST THINNER
Thinner with high pure solvents to dilute the Ecoresist in function of the application system.



ECORESIST DEVELOPER
Colorless water based Developer to remove the not exposed area.

LASER COATING



IR THERMAL RESIST
Infrared Laser Photoresist. Positive infrared laquer for Copper. Absorption at 830nm. Suitable for spray and ring coating. High resolution power.



THERMAL RESIST THINNER
Thinner with high pure solvents to dilute the Thermal Resist Thinner in function of the application system.



THERMAL RESIST DEVELOPER
Colorless water based Developer to remove the not exposed area.



THERMAL RESIST STRIPPING SOLUTION
Stripping and Washing Solution for Laser Coating.

ENGRAVING & ETCHING



REPROLASER B-212
Coating lacquer for YAG Laser ablation on Copper surface. Suitable for Spray and Ring Coating application. No Pre-etching with Chromic Acid required.



REPROLASER B-200
Standard Coating lacquer for YAG and Carbon Dioxide Laser ablation on Steel surface. Suitable for Spray and Ring Coating application.



REPROLASER R6V
Blue coating for Carbon Dioxide Laser ablation. Suitable for Spray and Ring coating of steel cylinders. High acid resistance.



REPROLASER THINNER
Thinner with high purity solvents to dilute Reprrolaser lacquers in function of the application system.



REPROLASER UV-RP1
Positive Photoresist for UV Laser exposing. UV absorption at 405 nm. Low viscosity polymer with high resolution, suitable for fine job (security) on Copper. Water based developer.



REPROLASER UV THINNER
Thinner with high purity solvents to dilute the Reprrolaser UV in function of the application system.



REPROLASER UV DEVELOPER
Colourless water based Developer to remove the not exposed area.



STRIPPING SOLUTION
Stripping and Washing Solution for all the type of Photoresist and Laser Coating.

ENGRAVING & ETCHING

ETCHING



DEGREASING PASTE BEFORE ETCHING

Very small particle size abrasive paste to degrease the cylinder surface, ready to be etched, to have the surface clean. It allows a uniform etching start.



COVERING BITUMEN

Protective Coating solution with high acid resistance, suitable to protect the cylinder surface during etching. Dilutable with petrol.



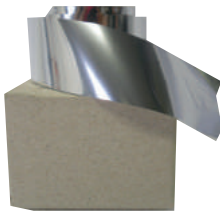
REPROLAC

Protective Lacquer for etching process, suitable for Copper and Steel. Alcohol based solution.



PHOTORESIST PAPER FILTER

Paper Filter suitable for the Photoresist filtration after dilution before use.



JOINT TAPE

Invisible tape joint kit products. Very thin aluminium tape to avoid blurring, suitable for the preparation of a rectilinear invisible joint on cylinders.



JOINT TAPE ADHESIVE

Liquid Adhesive to be applied at Joint Tape for the invisible joint procedure.



JOINT TAPE PRODUCT "B"

Special black coating especially designed for Joint Tape masking for the second part of the cylinder exposition.



JOINT PRODUCT "A" AND "B"

Peelable Black Coating and Transparent Dark Coating for invisible joint procedure. Product A to apply as first coating; after the Product "B" application, it is possible to remove it by peeling. Product B to apply on product A as second coating.



ELECTROLYTIC ETCHING SOLUTION (Electrograv)

Highly conductive saline solution, suitable for cylinders electrolytic etching. Without current it does not affect the Copper. Product is concentrated.

ENGRAVING & ETCHING



IRON CHLORIDE TYPE "N" 47 Bè
Concetrate Iron Chloride solution, stabilized and buffered, with constant free acidity, suitable both for auto typical and conventional etching. No Copper contained.



IRON CHLORIDE ADDITIVE (IRON ETCHING)
Additive used to accelerate the etching process on steel cylinders. It has the characteristic to get an homogeneous chemical attack.



SIDE ETCHING CONTROL ADDITIVE
Additive to reduce the "Side etching effect" with Iron Chloride etching solution.



DEOXIDIZER IN
Product at high removing power, suitable for removing inorganic etching residues. It perfectly cleans the cells enabling a perfect setting of the Chrome. No Chrome Salts contained



FILM CLEANER
Cleaning solution for Polyester and photographic films. High evaporation rate.



ANTISTATIC SOLUTION
Alcoholic solution containing substances suitable to eliminate the static electricity from polyester and photographic films.



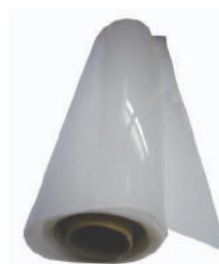
PLASTIC FOR COATING RINGS
Solvent proof plastic film for the preparation of the rings for coating machine to apply the Photoresist or Laser Lacquers on the cylinders.



EXPOSITION CONTROL SCALE
Continuous tone gray scale for the calibration of exposing time of the Photoresist. Graduated step value.



FELT TIPPED PEN FOR BITUMIZATION
Felt Tipped pen to apply acid proof ink for etching protection of Copper surface. Available with fine and large point.



POLYESTER TENSIONING FILM (ASTRALON)
Polyester Tensioning film for cylinder exposing.

ENGRAVING & ETCHING



PE EXTENSIBLE FILM
Polyethylene Extensible Film for cylinder shaft and mechanical part protection from chemical corrosion. Available with 125 mm and 250 mm H.

CYLINDER RETOUCHING



PICKLING SOLUTION RT
Alkaline Solution for Anodic and Cathodic degreasing for local corrections (retouching) on cylinder surface.



ACTIVATOR RT
Activator for local correction for Chrome plated surfaces. It removes the Chrome passive coat, allowing a perfect following deposition with the depassivator RT.



DEPASSIVATOR RT
Highly buffered concentrated solution for local corrections. By the deposition of a light metallic coating, it makes the Chrome surface suitable for following acid Copper deposition. Suitable also for small retouching surface; it avoids burning deposit.



COPPER PLATING RT
Concentrated Copper electrolyte for local corrections (retouching) on cylinder surface.



NICKEL PLATING RT
Concentrated Nickel electrolyte for local corrections (retouching) on cylinder surface.



CHROME DEPASSIVATOR
Highly buffered concentrated solution for local corrections. By the deposition of a light metallic coating, it makes the Chrome surface suitable for following acid Copper deposition. Suitable for Magazine Printing with large retouching area.

ENGRAVING & ETCHING



CHROMR ETCHING
Retouching solution for Magazine Printing to etch the Chrome surface to increase the cells volume.



DEPTH REDUCER TYPE "MINIMUM, MEDIUM, MAXIMUM"
Retouching Lacquer for Magazine Printing, to reduce the cells volume. Insoluble in Toluene and aromatic solvents. Available with three different reducing power.



SIGMA RE-ETCHING LACQUER
Antiacid protecting ink for cylinders re-etching in retouching operation. Applied on the surface with a rubber roller. Long drying time.



UV RE-ETCHING LACQUER
UV Antiacid protecting ink for cylinders re-etching in retouching operation. Applied on the surface with a rubber roller. Hardened with UV exposition.



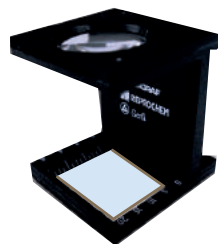
RETOUCHING STONE
Fine grain stone for cylinder retouching. Suitable for cylinder retouching after Copper local deposition.



GRAVER FOR CYLINDER RETOUCHING
Hard steel graters with different dimension for manual cylinder retouching.



FIBER GLASS BRUSHES
Fine Fiber Glass Brush for etched cell cleaning.
It is possible to remove Copper Oxide or dried ink from the cells. Suitable with 20 and 40 mm diameter.



MAGNIFICATION LENS
Magnification Lens for cell control. 8X



CELLULOSE PAPER
Cellulose paper for cylinder cleaning before and after Photoresist application. It does not leave fibers or particles on the cylinder. Supplied in boxes or in rolls.



EDGES CLEANING BRUSHES
Lamellar brushes to clean the edges and the electrical contact points of the cylinder. It removes the oxide allowing a better current flow.